ABSTRACT

The invention concerns a method of encapsulating on its support (1) with the use of a hardenable material an electronic assembly formed from an integrated circuit (2) and its wires (213,214,215).

It consists on one hand of positioning on the support, around the electronic assembly, a frame (6), and in that it consists on the other hand of putting into the frame, through its accessible opening, the necessary quantity of encapsulation material to obtain the final encapsulation, the said material being chosen among those which are capable of adopting a liquid state between the moment when they are put into the frame and before their hardening, so that, while it is in the liquid state, the material spreads under gravity into the whole of the frame and adopts the shape of the interior edge of the frame by capillary action, the encapsulation thus taking its final shape before hardening, and in that the material is hardened, and in that the frame is removed after hardening of the material.

Fig. 3

This Sheet Has Been Replaced

